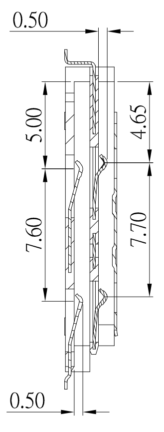
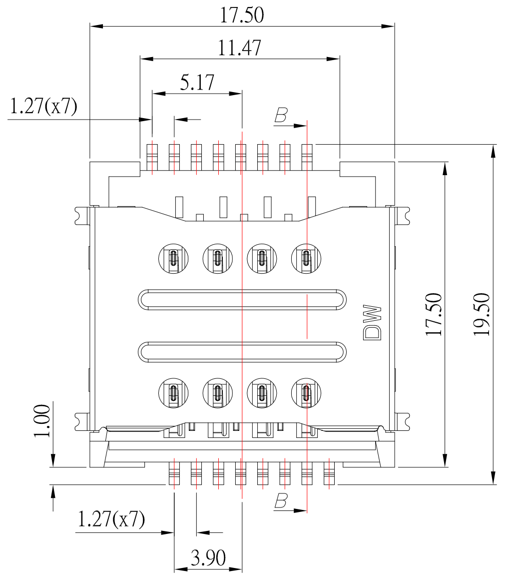
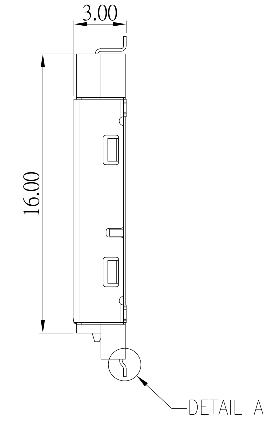
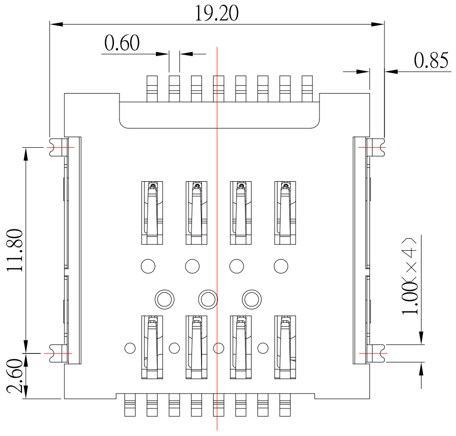
RoHS Compliant

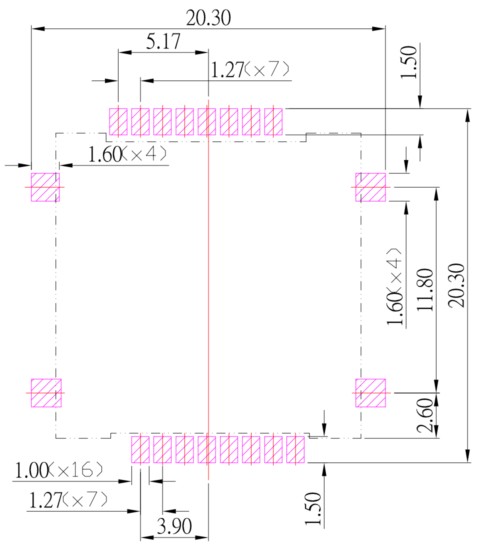


SECTION B–B

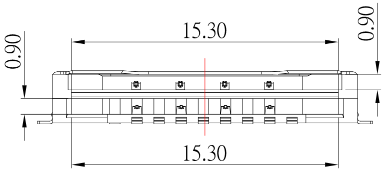


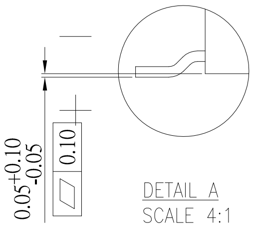






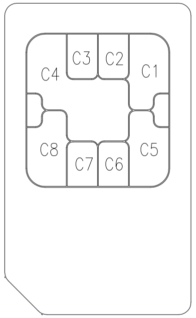
P.C.B LAYOUT MOUNTING PATTERN



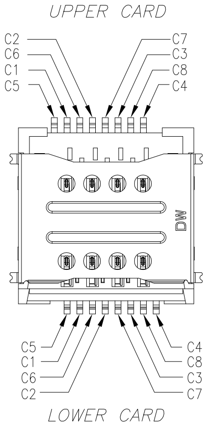


DETAIL A
SCALE 4:1

C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED



SIM CARD CIRCUIT



MATERIALS:
1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : COPPER ALLOY
3. SHELL : SUS

Finish:
1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:
1. INSULATION RESISTANCE : 1000MΩ MIN.
2. CONTACT RESISTANCE : 50mΩ MAX.
3.Dielectric Withstanding Voltage:350V AC
4.Durability:3000 cycles

ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT
建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY: Jack Lu	DATE 02/27/19	MAT'L		TITLE	CONNECTOR	
CHECKED BY: Jacky Chen	DATE 02/27/19	FINISH		MODLE	雙層SIM卡座H3.0	
APPROVED BY: Tony Kao	DATE 02/27/19	SCALE	1 : 1	DWG NO.	SIM-216D202-S267	SIZE A4
		SHEET NO.	1 of 1	PART NO.	SIM-216D202-S267	VER R